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Advances and Trends in Microelectronic Packaging

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Abstract
After a short introduction, the most important problematical issues are presented. The paper – intended to inform the non-specialists and decision makers – explores advanced packaging solutions for next generation microelectronics in key applications areas.

Keywords: Electrochemical processing, ITRS packaging requirements of IC, SMT, MEMS, NEMS, 3D, flexible circuits, reliability.

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